

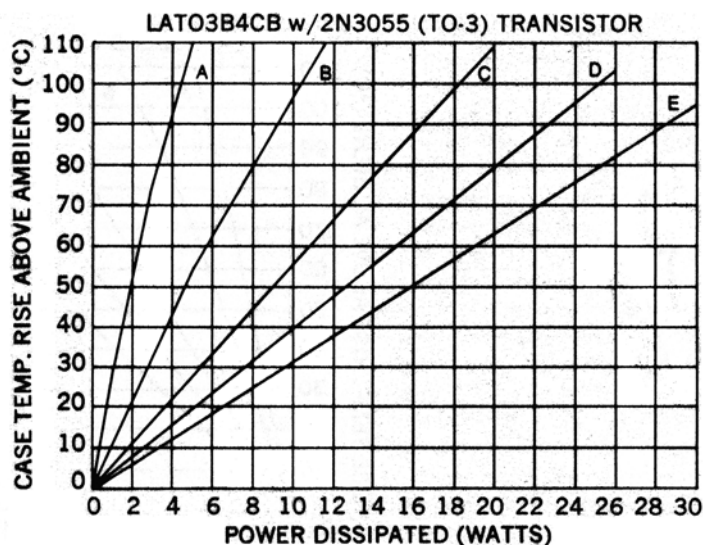
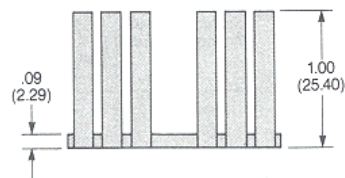
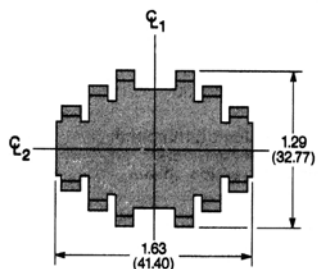
### METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LA-B4

Natural Conv. ( $^{\circ}\text{C}/\text{W}$ ): 10.3

Forced Air ( $^{\circ}\text{C}/\text{W}$ ): 3.2

Mounting Envelope: 1.63" x 1.29" x 1.00"



#### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

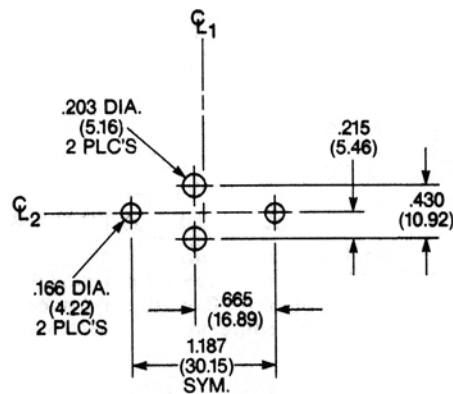
- Thermal Resistance Case to Sink is 0.1-0.3  $^{\circ}\text{C}/\text{W}$  w/Joint Compound.
- Derate 0.7  $^{\circ}\text{C}/\text{watt}$  for unplated part in natural convection only.

## Ordering Information

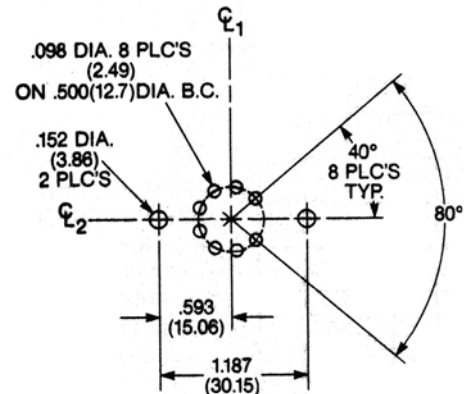
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
LA000B4U	LA000B4CB	LA000B4B	Undrilled	--	12.9
LAT03B4U	LAT03B4CB	LAT03B4B	TO-3	2	12.9
LAIC3B4U	LAIC3B4CB	LAIC3B4B	TO-3 IC	4	12.9
LA407B4U	LA407B4CB	LA407B4B	TO-3 (4-pin)	5	12.9
LA394B4U	LA394B4CB	LA394B4B	Universal	8	12.9

### HOLE PATTERNS

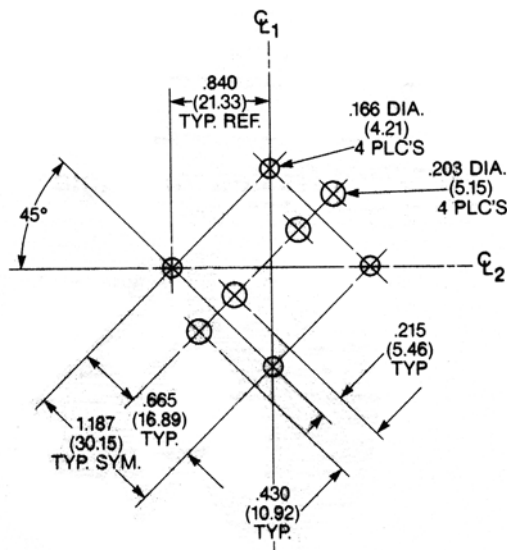
2. Hole Pattern no. 236 accommodates TO-3s. Available in LA-B series heat dissipators only.



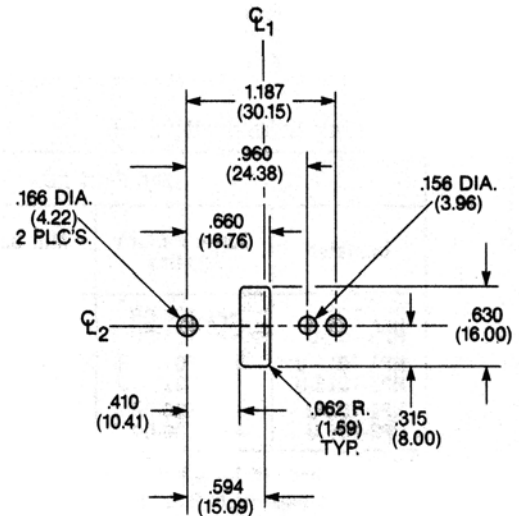
4. Hole pattern no. 237 accommodates To-3 ICs. Available in LA-B series heat dissipators only.



5. Hole pattern no. 407 accommodates TO-3s (4-pin). Available in LA-B series heat dissipators only.



8. Hole pattern no. 394 (universal) accommodates TO-3s, TO-66s, TO-126s, TO-127s, or T-220s. Available in LA-B series heat dissipators only.



### CTS IERC, Heat Sinks and Thermal Management Solutions

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